

R E M A R K S

Applicants have amended their specification in light of the prosecution history of prior application Serial No. 09/392,568, and to refer to this prior application Serial No. 09/392,568 consistent with the requirements of 35 USC §120. It is respectfully submitted that these amendments to the specification do not add new matter to the application.

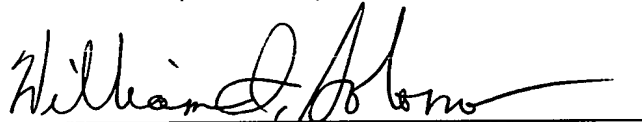
Entry of the present amendments, and examination of the above-identified application on the merits subsequent thereto, in due course, are respectfully requested.

Attached hereto is a marked-up version of the changes made in the specification by this Preliminary Amendment. This marked-up version is on the attached pages, the first page of which is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

To the extent necessary, applicants petition for an extension of time under 37 CFR §1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (854.37558VX2) and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP



William I. Solomon
Registration No. 28,565

WIS:alw
(703) 312-6600

ATTACHMENT A

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

Paragraph bridging pages 2 and 3 has been amended as indicated below:

Japanese Patent Application Laid-Open No. 6-41773 discloses a technique in which an anti-adsorption agent (such as NTPO, EDTPO, EDDPO, or the like) is added to an aqueous solution containing an alkaline component such as ammonium hydroxide, hydroxide of alkaline metal (KOH or [NAOH] NaOH), choline, or the like, thereby to restrict adsorption of metal into the wafer surface.

Paragraph at page 7, lines 8-17, has been amended as indicated below:

According to a second aspect of the present [inveniton] invention, there is provided a method of manufacturing a semiconductor integrated circuit device, comprising steps of (a) cleaning a surface of a silicon wafer with use of a processing solution containing hydrogen peroxide, hydracid fluoride salt, and [wafer] water, (b) subjecting the silicon wafer to a heat treatment thereby to form a gate oxide film on the surface of the silicon wafer, and (c) patterning a conductive film deposited above the gate oxide film, thereby to form a gate electrode.

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The heading at page 10, line 17, has been amended as indicated below:

DESCRIPTION OF THE PREFERRED [EMBDIMENTS] EMBODIMENTS

Paragraph on page 13, lines 7-17, has been amended as indicated below:

Next, as shown in FIG. 4, a silicon oxide film 7 having a film thickness of about 800 nm is deposited, for example, by a CVD method using oxygen and tetraethoxysilane as a [sauce] source gas. Thereafter, as shown in FIG. 5, the silicon oxide film 7 is polished by a Chemical Mechanical Polishing (CMP) method. As the silicon oxide film 7 remains only inside the groove 5a with using the silicon nitride film 3 as a polishing stopper, an element separation 5 is formed. Subsequently, a heat treatment at about 1000 °C is carried out to densify (sinter) the silicon oxide film 7 in the element separation groove 5.

Paragraph bridging pages 15 and 16 has been amended as indicated below:

The wafers 1 which have been loaded to the loader 101 of the cleaning/oxide-film-forming device 100 are transferred to the cleaning chamber 102, in units of every one or two sheet, and are dipped into a processing solution composed of a hydrogen peroxide, a hydracid salt fluoride and water. Here, the [hydrogen] hydracid salt fluoride is, for example, tetraalkyl ammonium fluoride such as tetramethyl ammonium fluoride, tetraethyl ammonium fluoride, or ammonium fluoride.

